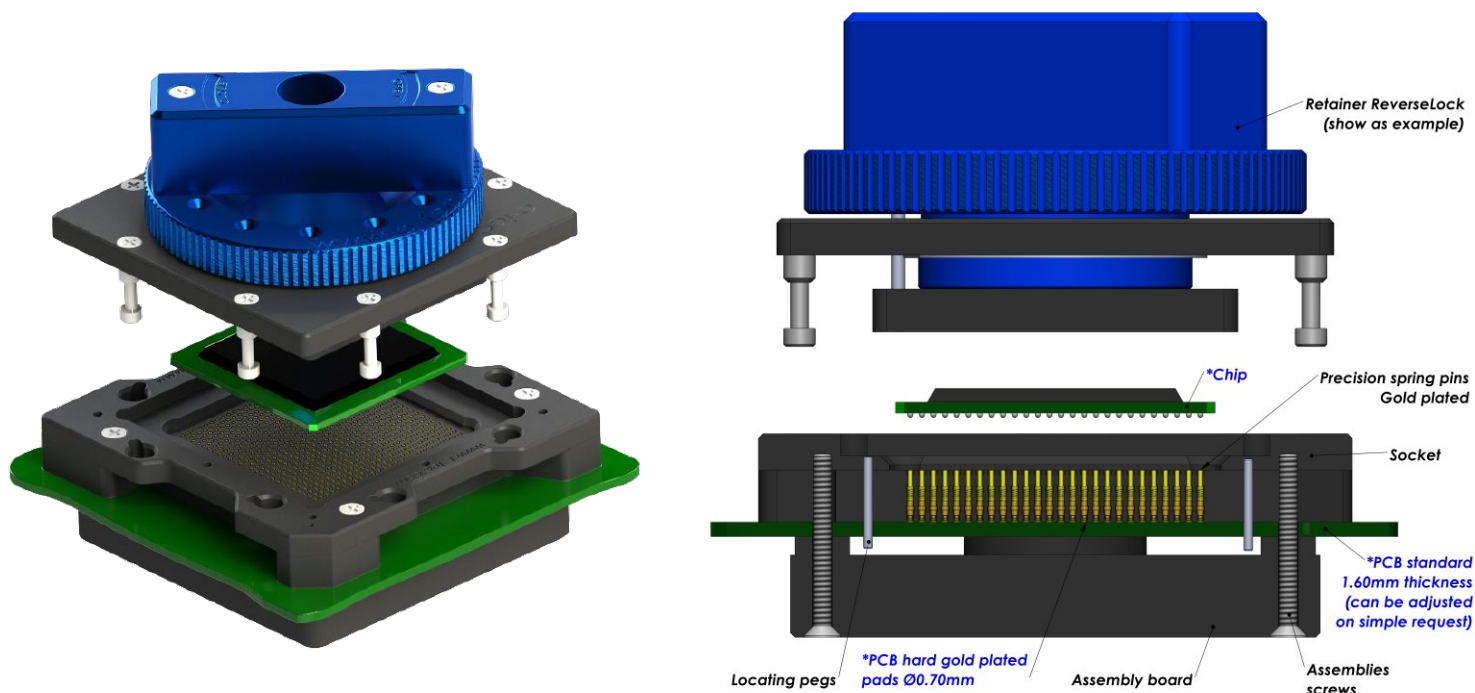
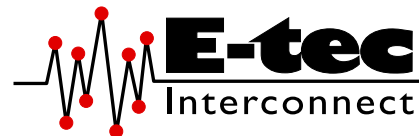


Probe Pin Solderless Compression Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package

1.27 mm pitch (from 1.27 mm upwards)



E-tec Interconnect AG is the world leading Test socket manufacturer

Probe Pin (Pogo) Solderless compression Test Sockets type are available for any chip size and pitch and are attached with 2, 4 or 8 screws to the PCB. The assembly board ensures perfect coplanarity of the socket. Contact reliability is guaranteed with spring loaded gold plated contacts, which are pressed onto gold plated PCB pads. Probe Pin (Pogo) Solderless compression type sockets are available with all retention systems. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket.

Contacts Specifications				
Contact type code	1290	1291	1294	1298
Application	Standard	High Frequency + Long Live	Frequency	Frequency
Mounting	Solderless	Solderless	Solderless	Solderless
Bandwidth (GHz@-1dB)	3 GHz	37.5 GHz	13.3 GHz	23.7 GHz
Contact resistance	<100 mOhm	45 mOhm	25 mOhm	25 mOhm
Chip contact tip shape	Single Point tip Concave tip	Crown tip	Single Point tip	Single Point tip
PCB tip shape	Single Point tip	Single Point tip	Spring	Spring
Force	25 gr	35 gr	25 gr	25 gr
Current rating	2.2 A	3 A	5 A	2.6 A
Capacitance pF	<1 pF	0.43 pF	0.76 pF	0.50 pF
Inductance nH	<2 nH	0.82 nH	1.73 nH	2.03 nH
Impedance Ohms	48 Ω	41 Ω	42.8 Ω	67.5 Ω
Temperature range	-55°C to +150°C	-40°C to +120°C	-55°C to +150°C	-55°C to +150°C
Mating cycles	100 K	300 K	100 K	100 K

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